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**REWORKABLE AND THERMALLY  
CONDUCTIVE ADHESIVE AND USE THEREOF**

**ABSTRACT OF DISCLOSURE**

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Reworkable thermally conductive adhesive composition comprising a cured reaction product from a diepoxide wherein the epoxy groups are connected through an acyclic acetal moiety, a cyclic anhydride and a thermally conductive filler are provided and used to bond semiconductive devices to a chip carrier or heat spreader.

TOP SECRET